MDPU Series
Molding SMD Power Inductors

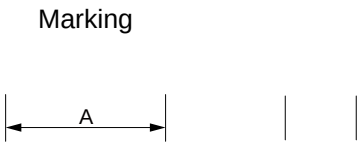
FEATURES

- Halogen Free & ROHS compliant.
  Low profile and low DCR.
- Magne cally Shielded construc on, low EMI.
- Frequency range up to 3MHz.
- Minimized acous c noise and minimized leakage flux noise.
- High current carrying capacity, Low core loss.
  Flat wire: high u liza on of winding space delivers low DC resistance.
  Opera ng temperature: -55 to +125 °C

APPLICATION

- AI Servers, Data Centers, GPU/AI Accelerators.
- Desktop Motherboards, CPU/GPU Power Delivery.
- Mul -phase VRM, High-current DC-DC Converters.
  Networking Equipment, Communica on Infrastructure.

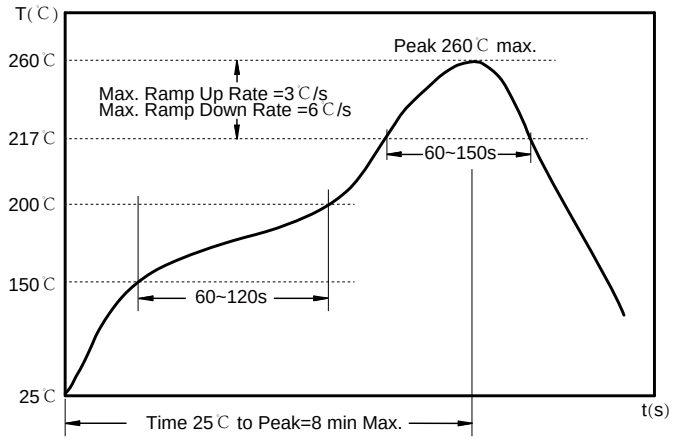
Dimensions: [mm]



	4.2±0.2	2.0 max	1.2±0.3	4.3±0.3	1.6	4.5
	5.1±0.3	3.0 max	1.6±0.3	5.3±0.3	1.7	5.5
	6.4±0.4	3.0 max	1.9±0.4	6.6±0.4	2.3	7.0

Electrical Properties:

Soldering Reflow:



Preheat condition: 150 ~200 ℃/ 60~120 sec.

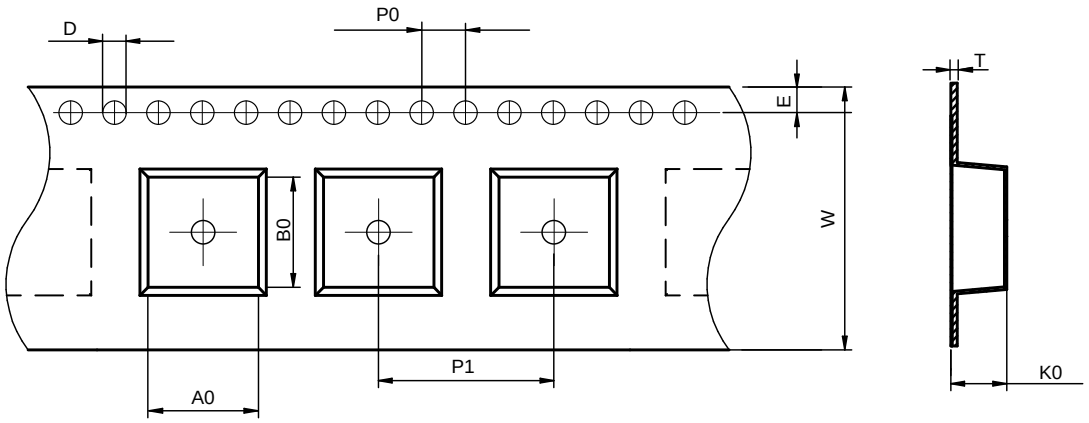
Allowed time above 217 ℃: 60~150 sec.

Max temperature: 260 ℃.

Time within 5 ℃ of actual Peak Temperature: 30 sec max.

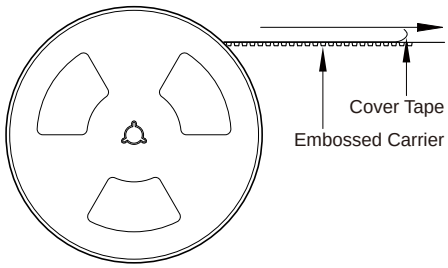
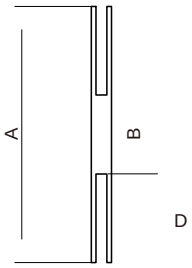
Packaging Information:

Tape Dimension：[mm]



Series	D typ.	P0 typ.	P1 typ.	W typ.	E typ.	A0 typ.	B0 typ.	K0 typ.	T typ.
0420	1.5	4.0	8.0	12.0	1.75	4.4	4.4	2.5	0.35
0530	1.5	4.0	8.0	12.0	1.75	6.0	5.7	3.3	0.35
0630	1.5	4.0	12.0	16.0	1.75	7.1	6.9	3.3	0.35
405060	1.5	4.0	8.0	16.0	1.75	4.6	5.6	6.3	0.40
4860	1.5	4.0	12.0	16.0	1.75	5.2	5.4	6.3	0.40
130806	1.5	4.0	12.0	24.0	1.75	7.3	13.1	6.3	0.40

Product Marking:

Marking	Printing (Inductance)

Reel Dimension：[mm]